2SK3228

Silicon N Channel MOS FET High Speed Power Switching

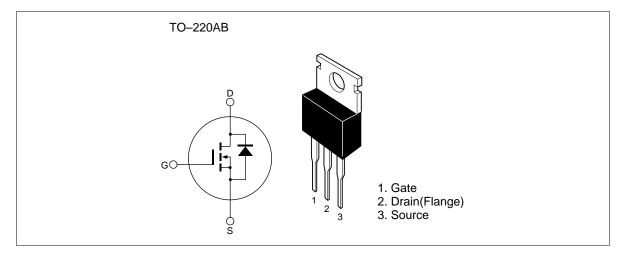
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ADE-208-765A(Z) Target specification 2nd. Edition December 1998

Features

- Low on-resistance $R_{DS(on)} = 6m\Omega \text{ typ.}$
- Low drive current
- 4V gate drive device can be driven from 5V source

Outline





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Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	Ratings	Unit
Drain to source voltage	V _{DSS}	80	V
Gate to source voltage	V _{GSS}	±20	V
Drain current	I _D	75	A
Drain peak current	I *1 D(pulse)	300	A
Body-drain diode reverse drain current	I _{DR}	75	A
Avalanche current	I _{AP} *3	50	A
Avalanche energy	E _{AR} *3	181	mJ
Channel dissipation	Pch*2	100	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

- Note: 1. PW \leq 10 μ s, duty cycle \leq 1 %
 - 2. Value at Tc = 25°C
 - 3. Value at Tch = 25° C, Rg $\geq 50\Omega$

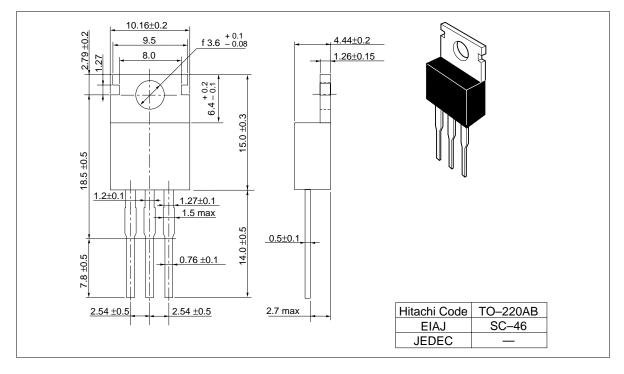
Electrical Characteristics ($Ta = 25^{\circ}C$)

Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	80	_	_	V	$I_{\rm D} = 10 {\rm mA}, \ V_{\rm GS} = 0$
Gate to source leak current	I _{GSS}	_	_	±0.1	μΑ	$V_{GS} = \pm 20V, V_{DS} = 0$
Zero gate voltege drain current	I _{DSS}	_	_	10	μΑ	$V_{DS} = 80 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	$V_{\rm GS(off)}$	1.0	_	2.5	V	$I_D = 1 \text{mA}, V_{DS} = 10 V^{*1}$
Static drain to source on state	R _{DS(on)}	_	6.0	7.5	$m\Omega$	$I_D = 40A, V_{GS} = 10V^{*1}$
resistance		_	8.0	12	mΩ	$I_D = 40A, V_{GS} = 4V^{*1}$
Forward transfer admittance	y _{fs}	55	90	_	S	$I_D = 40A, V_{DS} = 10V^{*1}$
Input capacitance	Ciss	_	9700	_	pF	V _{DS} = 10V
Output capacitance	Coss	_	1250	_	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	_	290	_	pF	f = 1MHz
Total gate charge	Qg	_	150	_	nc	V _{DD} = 25V
Gate to source charge	Qgs	_	30	_	nc	$V_{GS} = 25V$
Gate to drain charge	Qgd	_	30	_	nc	$I_D = 75A$
Turn-on delay time	t _{d(on)}	_	80	_	ns	$V_{GS} = 10V, I_{D} = 40A$
Rise time	t _r	_	300	_	ns	$R_L = 0.75\Omega$
Turn-off delay time	t _{d(off)}	_	770	_	ns	
Fall time	t _f	_	370	_	ns	_
Body-drain diode forward voltage	V_{DF}	_	1.05	_	V	$I_F = 75A, V_{GS} = 0$
Body-drain diode reverse recovery time	t _{rr}	_	90	_	ns	$I_F = 75A, V_{GS} = 0$ diF/ dt =50A/ μ s

Note: 1. Pulse test

Package Dimensions

Unit: mm



Cautions

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